

DT1751H

Component Metallization

Description

DT1751H is a lead free silver paste for frontside conductor of chip-resistors, which with high silver content. DT1751H exhibits excellent solder ability, acid-resistant adhesion and electrical characteristics.

Key Features

- Excellent solder ability Excellent adhesion Excellent acid-resistant adhesion Excellent electrical characteristics



Typical Properties

Viscosity	200 – 400 kcps, Brookfield HBDV–III Ultra, SC4-14 spindle & 6R utility cup @ 10 rpm, 25°C
Solids	81.0 ± 1.0%

Recommended Processing Guide

Printing Parameters	200-400 Kcps BROOKFIELD HBDV-III Ultra SC4-14 spindle and 6R utility cup @ 10 rpm, 25°C
Drying Temperature	130 °C for 15 minutes, with exhaust system 150 °C for 10 minutes
Process Temperature (TDS)	peak temp: 750~850 °C dwell time:8~15 minutes
Recommended Thinner	Heraeus SRV-372

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Warranty

Material guaranteed to meet specifications for 6 months from date of manufacturing with proper storage.

Storage

Store in a dry, cool (5 - 25°C), dark place with container tightly shut. Allow paste to come to room temperature prior to opening. Spatulate well before using.

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